

# BYC15X-600

Rectifier diode, hyperfast

Rev. 01 — 29 November 2007

Product data sheet

## 1. Product profile

### 1.1 General description

Hyperfast, epitaxial rectifier diode in a SOD113 (2-lead TO-220F) plastic package.

### 1.2 Features

- Extremely fast switching
- Low reverse recovery current
- Reduces switching loss in associated MOSFET
- Low thermal resistance
- Isolated package

### 1.3 Applications

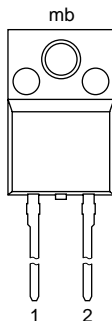

- Half-bridge or full-bridge switched-mode power supplies
- Half-bridge lighting ballasts
- Continuous Current Mode (CCM) Power Factor Correction (PFC)

### 1.4 Quick reference data

- $V_{RRM} \leq 600$  V
- $V_F = 1.32$  V (typ)
- $I_{F(AV)} \leq 15$  A
- $t_{rr} = 19$  ns (typ)

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode (k)		 001aaa020
2	anode (a)		
mb	mounting base; isolated		

SOD113 (2-lead TO-220F)

### 3. Ordering information

**Table 2.** Ordering information

Type number	Package		
	Name	Description	Version
BYC15X-600	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 2-lead TO-220 'full pack'	SOD113

### 4. Limiting values

**Table 3.** Limiting values

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	600	V
$V_{RWM}$	crest working reverse voltage		-	600	V
$V_R$	reverse voltage	square waveform; $\delta = 1.0$ ; $T_h \leq 100\text{ }^{\circ}\text{C}$	-	500	V
$I_{F(AV)}$	average forward current	square waveform; $\delta = 0.5$ ; $T_h \leq 25\text{ }^{\circ}\text{C}$	-	15	A
$I_{FRM}$	repetitive peak forward current	square waveform; $\delta = 0.5$ ; $T_h \leq 25\text{ }^{\circ}\text{C}$ ; $t_p = 25\text{ }\mu\text{s}$	-	30	A
$I_{FSM}$	non-repetitive peak forward current	$t = 10\text{ ms}$ ; sinusoidal waveform	-	200	A
		$t = 8.3\text{ ms}$ ; sinusoidal waveform	-	220	A
$T_{stg}$	storage temperature		-40	+150	$^{\circ}\text{C}$
$T_j$	junction temperature		-	150	$^{\circ}\text{C}$

5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; see <a href="#">Figure 1</a>	-	-	3.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	55	-	K/W

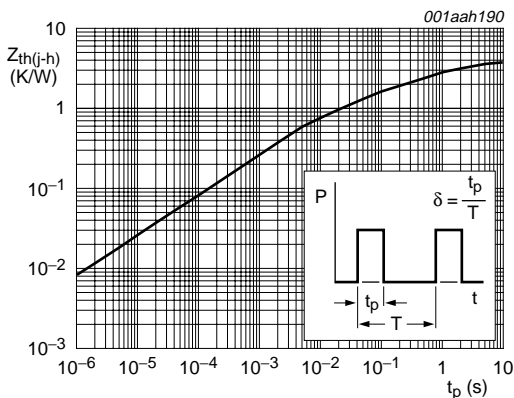


Fig 1. Transient thermal impedance from junction to heatsink as a function of pulse width

6. Isolation characteristics

Table 5. Isolation limiting values and characteristics

$T_h = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

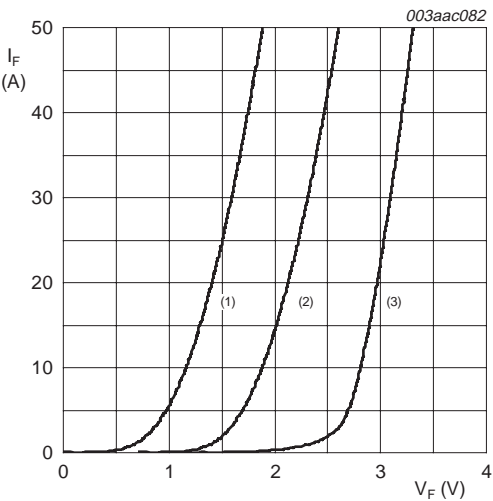
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	from all terminals to external heatsink; $f = 50\text{ Hz to }60\text{ Hz}$ ; sinusoidal waveform; relative humidity $\leq 65\%$ ; clean and dust free	-	-	2500	V
$C_{isol}$	isolation capacitance	from pin 1 (cathode) to external heatsink; $f = 1\text{ MHz}$	-	10	-	pF

## 7. Characteristics

**Table 6. Characteristics**

$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C; see <a href="#">Figure 2</a>	-	1.32	2.03	V
		I <sub>F</sub> = 30 A; T <sub>j</sub> = 150 °C; see <a href="#">Figure 2</a>	-	1.64	2.34	V
		I <sub>F</sub> = 15 A; see <a href="#">Figure 2</a>	-	1.89	2.9	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V	-	12	200	μA
		V <sub>R</sub> = 500 V; T <sub>j</sub> = 100 °C	-	1.1	3.0	mA
Dynamic characteristics						
t <sub>rr</sub>	reverse recovery time	I <sub>F</sub> = 1 A to V <sub>R</sub> = 30 V; dI <sub>F</sub> /dt = 50 A/μs; see <a href="#">Figure 3</a>	-	35	55	ns
		I <sub>F</sub> = 15 A to V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; see <a href="#">Figure 3</a>	-			
		T <sub>j</sub> = 25 °C	-	19	-	ns
		T <sub>j</sub> = 100 °C	-	32	40	ns
I <sub>RM</sub>	peak reverse recovery current	I <sub>F</sub> = 15 A to V <sub>R</sub> = 400 V; T <sub>j</sub> = 125 °C; see <a href="#">Figure 3</a>	-			
		dI <sub>F</sub> /dt = 50 A/μs	-	3.0	7.5	A
		dI <sub>F</sub> /dt = 500 A/μs	-	9.5	12	A
V <sub>FR</sub>	forward recovery voltage	I <sub>F</sub> = 15 A; dI <sub>F</sub> /dt = 100 A/μs; see <a href="#">Figure 4</a>	-	8	11	V



- (1)  $T_j = 150\text{ }^{\circ}\text{C}$ ; typical values
- (2)  $T_j = 150\text{ }^{\circ}\text{C}$ ; maximum values
- (3)  $T_j = 25\text{ }^{\circ}\text{C}$ ; maximum values

Fig 2. Forward current as a function of forward voltage

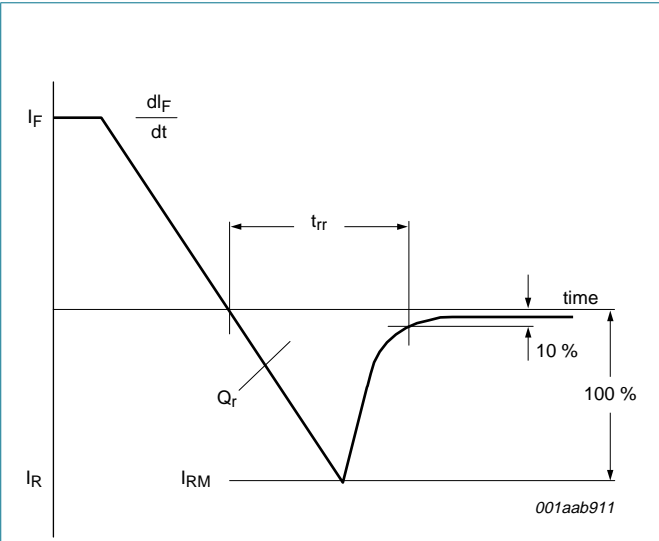


Fig 3. Reverse recovery definitions

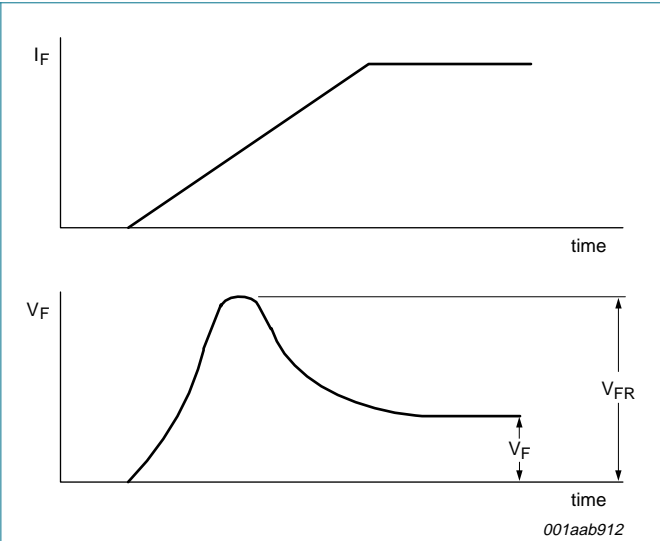
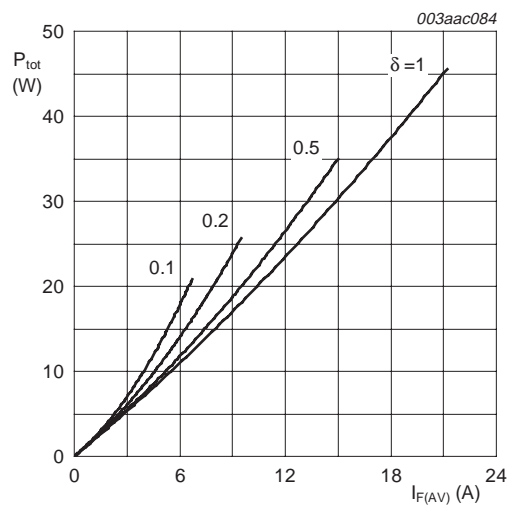
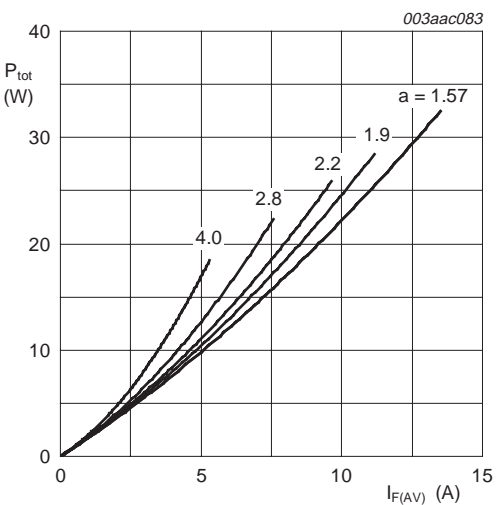


Fig 4. Forward recovery definitions



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$

Fig 5. Forward power dissipation as a function of average forward current; square waveform; maximum values



$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$

Fig 6. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

8. Package outline

Plastic single-ended package; isolated heatsink mounted;  
1 mounting hole; 2-lead TO-220 'full pack'

SOD113

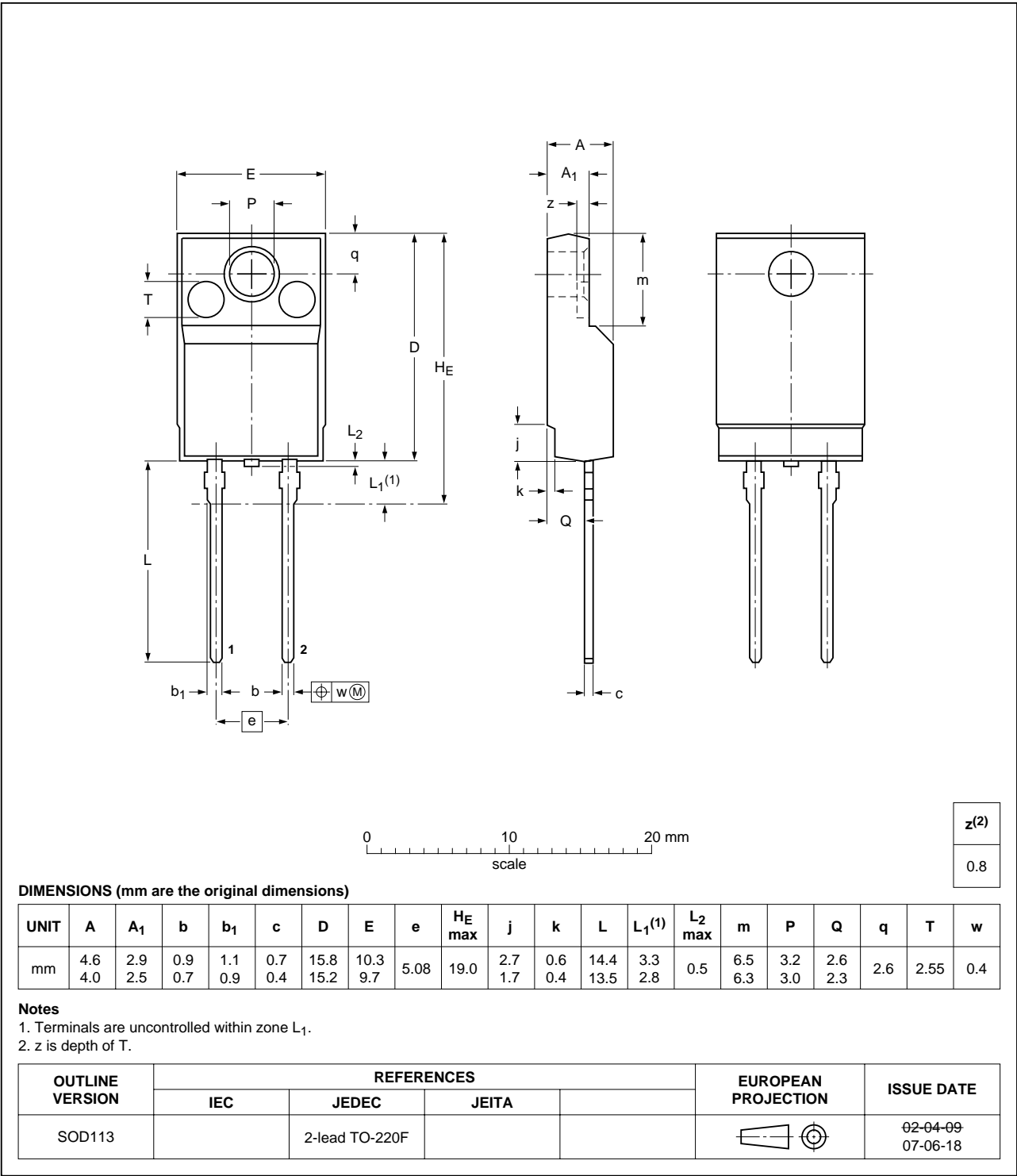


Fig 7. Package outline SOD113 (2-lead TO-220F)

9. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYC15X-600_1	20071129	Product data sheet	-	-



## 10. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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12. Contents

1 Product profile ..... 1

1.1 General description..... 1

1.2 Features ..... 1

1.3 Applications ..... 1

1.4 Quick reference data..... 1

2 Pinning information..... 1

3 Ordering information..... 2

4 Limiting values..... 2

5 Thermal characteristics..... 3

6 Isolation characteristics ..... 3

7 Characteristics..... 4

8 Package outline ..... 7

9 Revision history..... 8

10 Legal information..... 9

10.1 Data sheet status ..... 9

10.2 Definitions..... 9

10.3 Disclaimers..... 9

10.4 Trademarks..... 9

11 Contact information..... 9

12 Contents ..... 10



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